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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC112

Dual J-K Flip-Flops (with Preset and Clear)



ADE-205-435 (Z)
1st. Edition
Sep. 2000

Description

Each flip-flop has independent J, K, preset, clear and clock inputs and Q and $\overline{Q}$ outputs. This device is edge sensitive to the clock input and change state on the negative going transition of the clock pulse. Clear and preset are independent of the clock and accomplished by a low logic level on the corresponding input.

Features

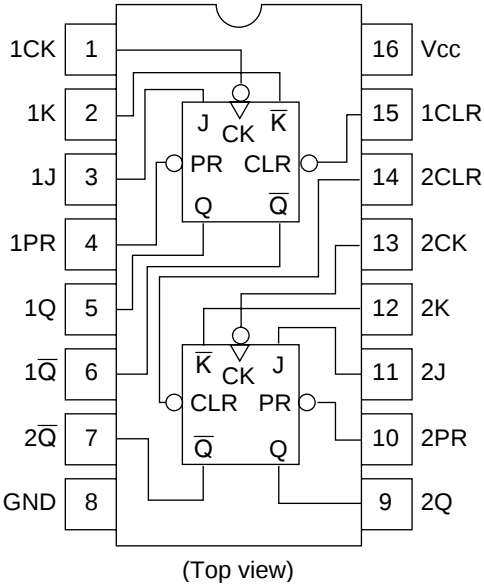
- High Speed Operation: t_{pd} (Clock to Q) = 17 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 2 μ A max (T_a = 25°C)

Function Table

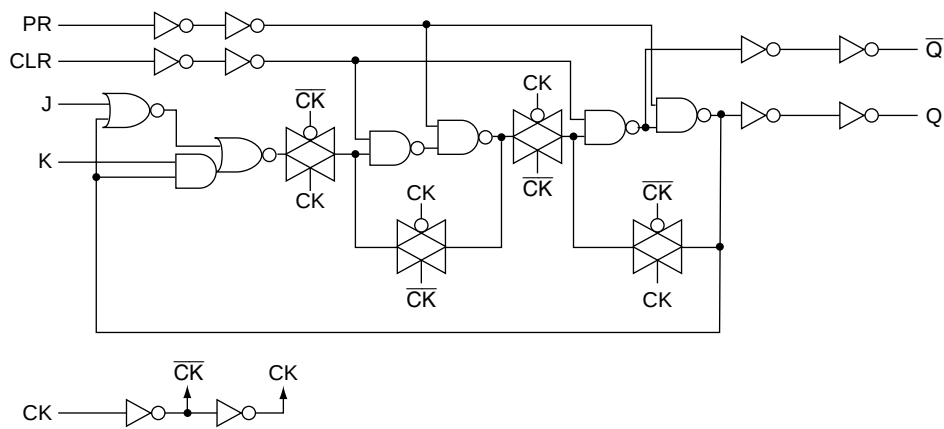
Inputs					Output	
Preset	Clear	Clock	J	K	Q	$\overline{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H* ¹	H* ¹
H	H		L	L	No Change	
H	H		L	H	L	H
H	H		H	L	H	L
H	H		H	H	Toggle	
H	H	L	X	X	No Change	
H	H	H	X	X	No Change	
H	H		X	X	No Change	

Note: 1. Q and $\overline{Q}$ will remain HIGH as long as Preset and Clear are Low, but Q and $\overline{Q}$ are unpredictable, if Preset and Clear go HIGH simultaneously.

Pin Arrangement



Logic Diagram (1/2)



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	2.0	—	20	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

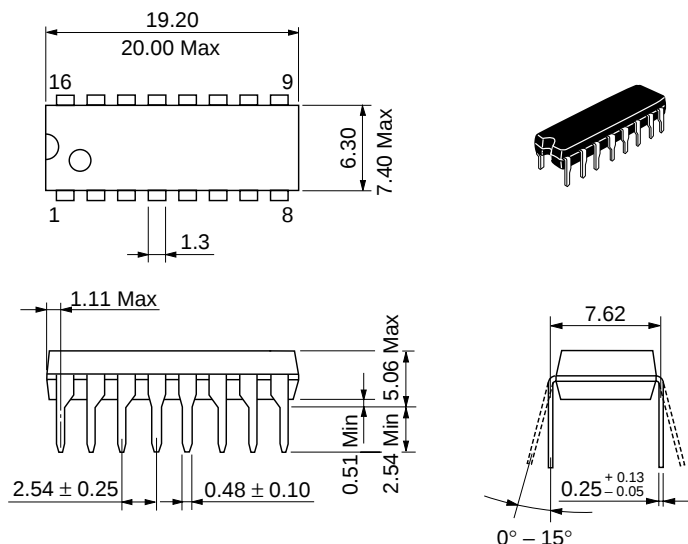
HD74HC112

AC Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Maximum clock frequency	f _{max}	2.0	—	—	6	—	5	MHz	
		4.5	—	—	30	—	24		
		6.0	—	—	35	—	28		
Propagation delay time	t _{PLH}	2.0	—	—	150	—	190	ns	Clock to Q or $\overline{Q}$
		4.5	—	17	30	—	38		
		6.0	—	—	26	—	33		
	t _{PHL}	2.0	—	—	140	—	175		Clear to Q or $\overline{Q}$
		4.5	—	15	28	—	35		
		6.0	—	—	24	—	30		
		2.0	—	—	140	—	175		Preset Q or $\overline{Q}$
		4.5	—	16	28	—	35		
		6.0	—	—	24	—	30		
Pulse width	t _w	2.0	80	—	—	100	—	ns	Clock, Clear
		4.5	16	9	—	20	—		
		6.0	14	—	—	17	—		
Setup time	t _{su}	2.0	100	—	—	125	—	ns	Data to Clock
		4.5	20	3	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t _h	2.0	5	—	—	5	—	ns	Clock to Data
		4.5	5	-2	—	5	—		
		6.0	5	—	—	5	—		
Removal time	t _{rem}	2.0	100	—	—	125	—	ns	Clear to Clock
		4.5	20	2	—	25	—		
		6.0	17	—	—	21	—		
Output rise/fall time	t _{TLH} t _{THL}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

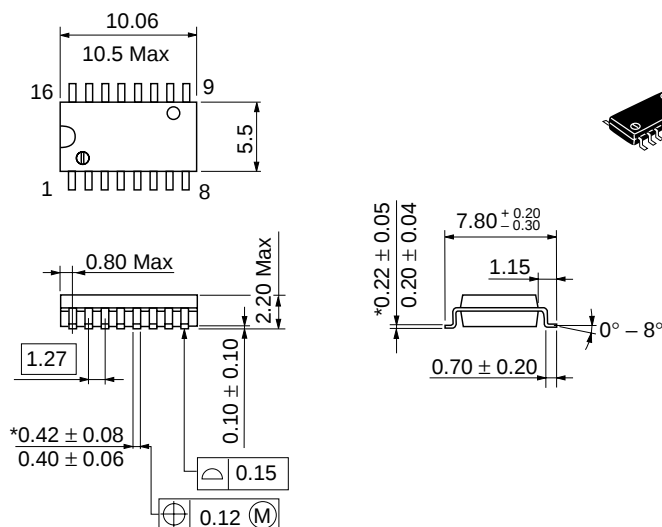
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

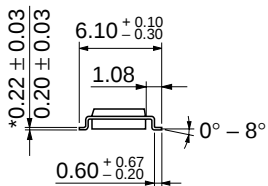
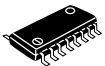
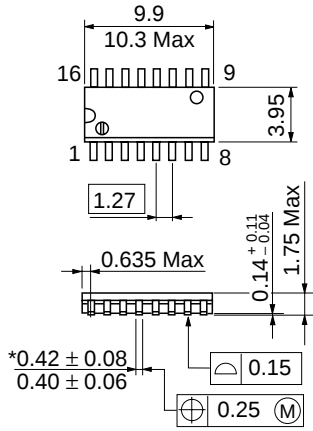
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

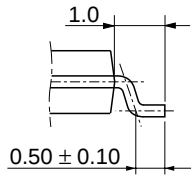
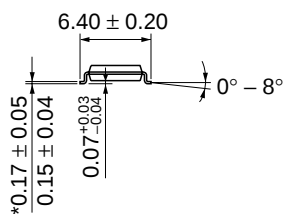
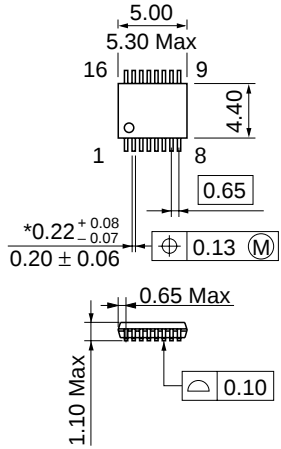
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-16DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

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